

Applicant(s)	John T. Gasner et al.	INFORMATION DISCLOSURE STATEMENT FORM PTO-1449
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Examiner Name	Unassigned H. Lee	
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Title: ACTIVE AREA BONDING COMPATIBLE HIGH CURRENT STRUCTURES

Sheet 1 of 1

U.S. Patent References				
Examiner Initials	Patent No.	Issue Date	Name	Filing Date
<i>Lee</i>	4,695,868	09/22/87	Fisher	12/13/85

Foreign Patent References				
Examiner Initials	Foreign Patent	Name	Publication Date	T
	Country No.			
	NONE			

Other References				
Examiner Initials	Author, Title, Date, Pages, etc.			
<i>Lee</i>	W. R. Anderson et al, "ESD Protection Under Wire Bonding Pads", EOS/ESD Symposium, 1999, pgs. 2A4.1-2A4.7.			
<i>Lee</i>	W. R. Anderson et al., "Reliability considerations for ESD protection under wire bonding pads", Microelectronics Reliability 41 (2001) pgs. 367-373.			
<i>Lee</i>	T. B. Ching et al., "Bond Pad Structure Reliability", Texas Instruments Incorporated, 1998 IEEE, pgs. 64-70			

Examiner Signature	<i>Hien May Lee</i>	Date Considered	10/25/04
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*Examiner: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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